

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/22/13788	
<b>1.3 Title of PCN</b>	IPAK Al wire line relocation from Shenzhen to Tongfu Microelectronics (China)	
<b>1.4 Product Category</b>	Power MOSFET HV, IGBT	
<b>1.5 Issue date</b>	2022-11-22	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Maurizio GIUDICE, Angelo RAO
<b>2.1.2 Marketing Manager</b>	Paolo PETRALI, Natale Sandro D'ANGELO
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Shenzhen (China), Tongfu Microelectronics (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	IPAK Al wire products are manufactured in Shenzhen (China)	IPAK Al wire products are manufactured in Tongfu Microelectronics (China)
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	IPAK Line Shenzhen (China) closure
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	By internal traceability and dedicated FG code
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-11-20
<b>7.2 Intended start of delivery</b>	2023-03-27
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13788 Binder1.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-11-22

**9. Attachments (additional documentations)**

13788 Public product.pdf  
 13788 IPAK AI wire line relocation from Shenzhen to TFME.pdf  
 13788 Binder1.pdf  
 13788 Comparison IPAK STS vs TFME.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD5NM60-1	
	STGD6NC60H-1	
	STU10NM60N	
	STU12N60M2	
	STU13N60M2	
	STU16N65M2	
	STU2NK100Z	
	STU5N95K3	
	STU6N62K3	
	STU6N95K5	
	STU7N105K5	
	STU7NM60N	
	STU8N80K5	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title** : IPAK AI wire line relocation from Shenzhen to Tongfu Microelectronics (China)

**PCN Reference** : ADG/22/13788

**Subject** : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STU5N95K3	STD2HNC60Z-1	STU13N60M2
STU2NK100Z	STU12N60M2	STD2NK90Z-1
STU7NM60N	STD5NM60-1	STU6N62K3
STD4NK80Z-1	STU8N80K5	STU6N95K5
STU16N65M2	STGD6NC60H-1	STU10NM60N
STU5N62K3	STU5N95K5	STU6N60DM2
STU7N60DM2	STU13NM60N	STU7N105K5



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